

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. – 4. (Canceled).

5. (Currently Amended) A ~~thin film manufacturing device which is~~ provided with for forming a wiring, comprising:  
a liquid drop ejecting device for ejecting a-liquid drops to onto a substrate by  
scanning on the substrate in at least first and second scanning movements; and  
a surface-treatment device for performing a surface-treatingment for a surface of  
the substrate wherein the device for performing a surface treatment performs a surface  
treatment such that ejected liquid drops are disposed on the substrate such that  
predetermined regular intervals are formed therebetween in the first scanning  
movement, the liquid drops ejected in the second scanning movement are disposed to  
fill the predetermined regular intervals, and the substrate is surface-treated by the  
surface treatment device so that a contact angle of the ejected liquid drops which are  
ejected from the liquid drop ejecting device with respect to the substrate is in a  
predetermined range.

6. (Currently Amended) A ~~thin film manufacturing device for forming~~  
wiring according to Claim 5, wherein the ~~surface treatment is performed such that the~~  
~~contact angle is in a range of 15° to 45°.~~

7. – 15. (Canceled).

16. (New) A device for forming wirings according to Claim 5, wherein the predetermined regular intervals are determined by controlling: a relative speed of the liquid drop ejecting device with respect to the substrate; and a frequency of the ejection by the liquid drop ejecting device.